IN THE SPECIFICATION:

Please change the paragraph starting at the bottom of page 3 as follows:

Referring to FIG. 1, a method for fabricating a peelable circuit board foil **200** is shown, in accordance with an embodiment of the present invention. A cross sectional view of the peelable circuit board foil **200** is shown in FIG. 2. At step **105** (FIG. 1) a metal support layer **205** (FIG. 2) and a conductive metal foil **210** (FIG. 2) are formed that are joined at a first surface of the metal support layer **205** and a second surface of the conductive metal foil **210** ~~surfaces~~ using an inorganic release material **215** (FIG. 2). This inorganic release material **215** retains its ability to separate the two metal layers **205**, **210** after exposure to high temperatures (used to add a crystallized dielectric layer to the peelable circuit board foil **200**, as described below with reference to FIGS. 3 and 4). The inorganic release material consists essentially of a co-deposited admixture of a metal and a non-metal, and may be formed using known techniques such as those described in US patent 6,346,335,B1 issued to Chen et al. on Feb. 12, 2002. In accordance with this embodiment of the present invention, the metal support layer **205** may be between 10 and 75 microns thick, and for most uses is between 30 and 70 microns thick; the conductive metal foil **210** may be between 5 and 25 microns thick and for most uses is between 10 and 20 microns thick; and the inorganic release material may be less than 0.030 microns thick. Because the present invention is for fabrication of a dielectric foil (and, ultimately, the formation of capacitors in a layer or layers of multi-layer printed circuit boards), the conductive metal foil **210** of the present invention is normally thicker than that used for conventional metal foils having a release layer (for example, see US patent 6,346,335). The optimum metal for the metal support layer **205** and the conductive metal foil **210** for most applications is copper or a copper alloy, but other metals such as nickel or a nickel alloy could be used.

Please change the paragraph starting below the middle of page 5 as follows:

At step **110** (FIG. 1), a first ~~second~~ surface **212** of the metal foil layer **210** may be coated with a high temperature anti-oxidant barrier **220** (FIG. 2), and the resulting coated first ~~second~~ surface (**221**) has a surface roughness less than 0.05 micron root mean square (RMS). The high temperature anti-oxidant barrier **220** is one that is effective to prevent any substantial oxidation of the conductive metal foil **210** during a later step in which a dielectric oxide is applied, pyrolyzed, and crystallized by known techniques, at temperatures as high as about 600 degrees centigrade, and differs from anti-tarnish coatings used for conventional peelable circuit board foils that perform well at temperatures below 100 degrees centigrade.

Please change the second paragraph starting on page 6 as follows:

Electroless or electrolytic nickel phosphorus is useful as the high temperature anti-oxidant in many applications. The phosphorous content of the nickel-phosphorous generally ranges from about 1 to about 40 wt% phosphorous, more specifically about 4-11 wt% and even more specifically about 6-9 wt%. Typically, the technique chosen to coat the conductive metal foil layer **210** will result in a second surface **207** (FIG. 2) of the metal support layer **205** also being coated with the same high temperature anti-oxidant barrier **225** (FIG. 2) to about the same thickness, but this is not a required result for the present invention. For example, a technique such as masking the second surface of the metal support layer **205** with a resist or other polymer material during the plating step would result in the high temperature anti-oxidant barrier being applied to only to the conductive metal foil **210** becomes joined to the metal support layer **205**, leaving the metal support layer **205** uncoated, is an acceptable alternative technique. In contrast to conventional peelable circuit board foils, for example the CopperBond® Thin Copper Foil distributed by Olin Corporation Metals Group of Waterbury, CT, for which the exposed first surface of the conductive metal foil may be intentionally roughened by a dendrite forming process, the resulting first surface of the conductive metal foil **210** of the present invention is kept smooth, with a roughness measurement less than 0.05 microns root mean square (RMS), and more preferably less than 0.01 micron RMS. Such smoothness can be achieved by known techniques that are used to form the conductive metal foil **210** and the high-temperature anti-oxidant barrier **220**. The peelable circuit board foil **200** formed by the method described with reference to FIG. 1 is conveniently able to be made in sizes commensurate with conventional printed circuit boards and handled and shipped without having to use expensive techniques to protect it from wrinkling or tearing during shipment, handling, and processing.